

**METHOD FOR THE ADHESION OF TWO ELEMENTS, IN PARTICULAR
OF AN INTEGRATED CIRCUIT, FOR EXAMPLE AN ENCAPSULATION
OF A RESONATOR, AND CORRESPONDING INTEGRATED CIRCUIT**

Abstract of the Disclosure

A method for attaching a first element to a second element is provided. The first element has a surface portion covered with a layer of silicon, and the second element has a surface portion covered with a layer of nickel. The method includes applying pressure so that the surface portions of the first and second elements are in contact with one another. A roughness between the surface portions is less than about 1 μm , and the first and second elements are heated within a range of about 250°C to 400°C.